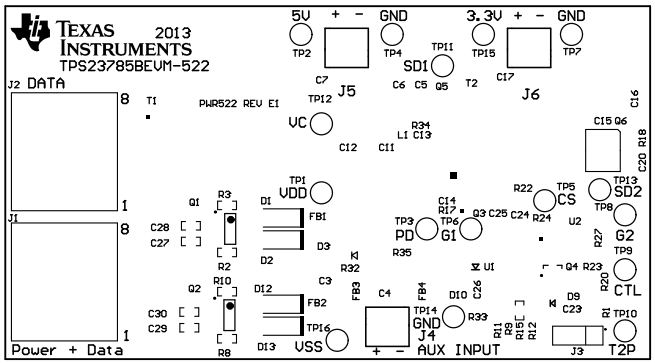
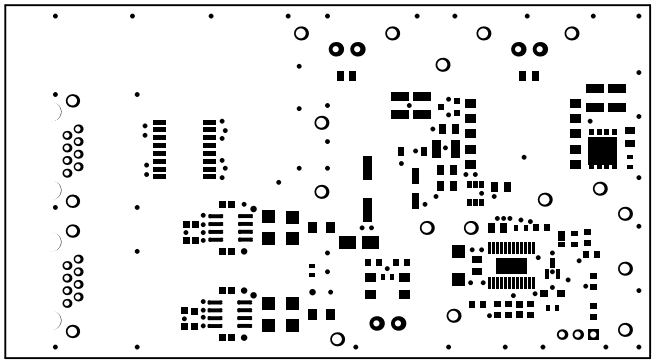
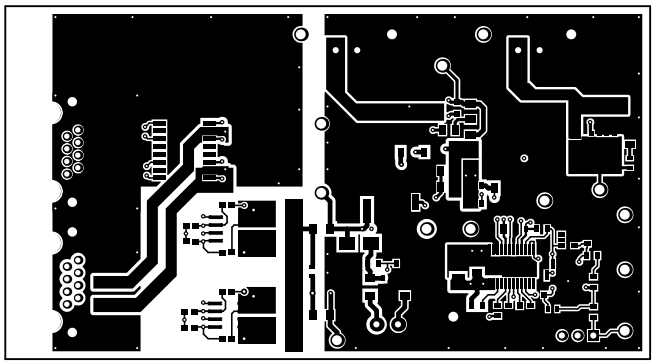


TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522	Rev. E1					S1								
Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright		PCB Dsgn: E. Wright		Modified Date: 12/12/12				Software: AltiumAD10				



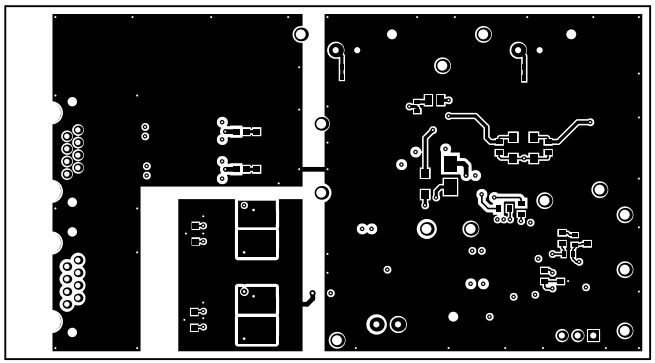
TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
	Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522 Rev. E1							M1						

Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright	PCB Dsgn: E. Wright	Modified Date: 12/12/12	Software: AltiumAD10



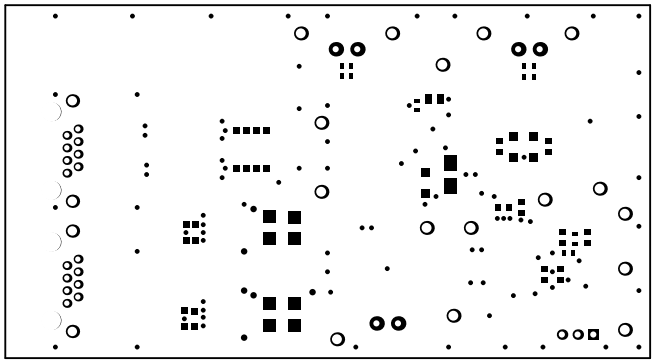
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522	Rev. E1	L1												

Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright	PCB Dsgn: E. Wright	Modified Date: 12/12/12	Software: AltiumAD10

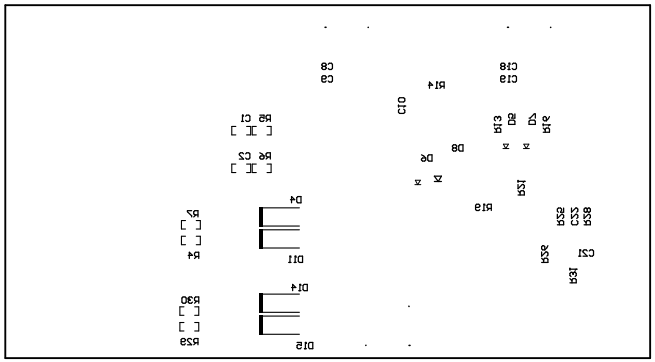


TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
	Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522 Rev. E1				L4									

Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright	PCB Dsgn: E. Wright	Modified Date: 12/12/12	Software: AltiumAD10



TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
	Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522 Rev. E1								M2					
Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright	PCB Dsgn: E. Wright	Modified Date: 12/12/12							Software: AltiumAD10		



TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
	Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522 Rev. E1						S2							
Date: 12/12/12	Filename: PWR522E1.pcbdoc		Engineer: E. Wright		PCB Dsgnr: E. Wright		Modified Date: 12/12/12				Software: AltiumAD10		

Layer Stack Up Detail for: PWR522E1.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top	(.GTL)	1.35mil	
			FR-4
Mid-Layer 1	(.G1)	1.4mil	
			FR-4
Mid-Layer 2	(.G2)	1.4mil	
			FR-4
Bottom	(.GBL)	1.35mil	
Bottom Solder Mask	(.GBS)		Solder Resist

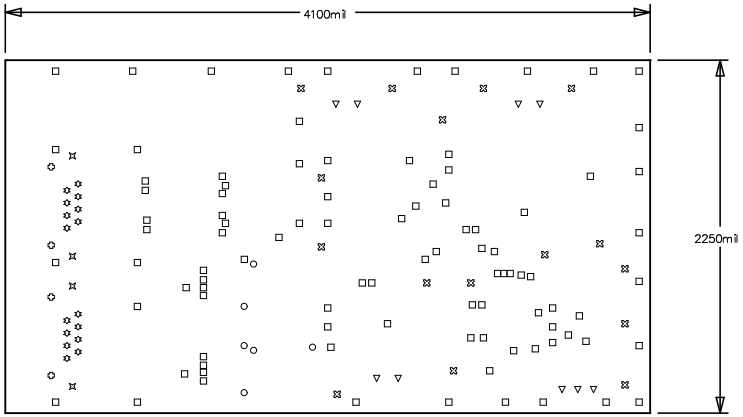
FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
☐ 0.031	■ LAYER 1	■ LAYER 1	■ 1 OZ.
■ 0.062	■ LAYER 2	■ LAYER 2	☐ 2 OZ.
☐ 0.093	☐ NONE	☐ NONE	☐ OTHER ____
☐ 0.125			____

DESIGN	TRACE/GAP SPACING	LAYER COUNT
☐ SMD	■ 0.010/0.010	☐ SINGLE SIDED
☐ THRU-HOLE	☐ 0.008/0.007	☐ 2 LAYER
■ MIX	☐ 0.006/0.006	■ 4 LAYER
		☐ OTHER ____

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	96	14mil (0.356mm)	PTH	Round
○	6	18mil (0.457mm)	PTH	Round
✡	16	35.039mil (0.89mm)	PTH	Round
▽	9	40mil (1.016mm)	PTH	Round
⌑	4	61.811mil (1.57mm)	PTH	Round
⊠	16	63mil (1.6mm)	PTH	Round
✪	4	127.953mil (3.25mm)	NPTH	Round
	151 Total			

Drill Table

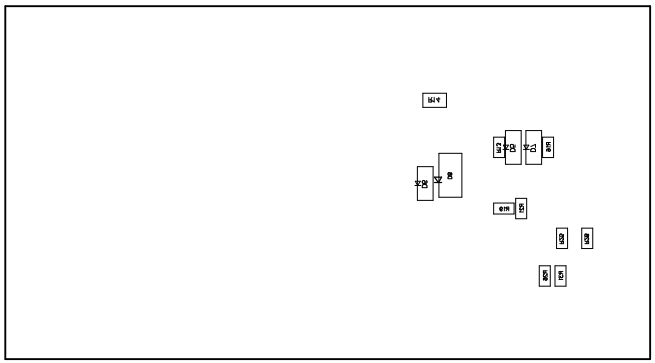


NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR
2. BASE LAMINATE: EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
	Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522 Rev. E1													FB

Date	Filename	Engineer	PCB Dsgnr	Modified Date	Software
12/12/12	PWR522E1.pcbdoc	E. Wright	E. Wright	12/12/12	AltiumAD10



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Mid1	Mid2	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PWR522	Rev. E1												BA	
Date: 12/12/12	Filename: PWR522E1.pcbdoc	Engineer: E. Wright		PCB Dsgn: E. Wright		Modified Date: 12/12/12						Software: AltiumAD10		

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